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December 2014

FCH150N65F

N-Channel SuperFET® II FRFET® MOSFET

650 V, 24 A, 150 mΩ

Features

- 700 V @ T_J = 150°C
- Typ. $R_{DS(on)}$ = 133 m Ω
- Ultra Low Gate Charge (Typ. Q_g = 72 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 361 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

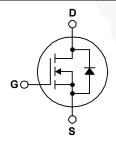
Applications

- LCD / LED / PDP TV Telecom / Server Power Supplies
- Solar Inverter
- · AC DC Power Supply

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET II FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FCH150N65F_F155	Unit
V_{DSS}	Drain to Source Voltage			650	V
1/	Coto to Course Valtage	- DC		±20	V
V_{GSS}	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V
,	Dunin Comment	- Continuous (T _C = 25°C)		24	
ID	Drain Current	- Continuous (T _C = 100°C)		14.9	Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	72	Α
E _{AS}	Single Pulsed Avalanche Energ	Single Pulsed Avalanche Energy (Note 2)		663	mJ
I _{AR}	Avalanche Current		(Note 1)	4.7	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	2.98	mJ
du/dt	MOSFET dv/dt			100	1//20
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	50	V/ns
D	Dawar Dissipation	$(T_C = 25^{\circ}C)$		298	W
P_{D}	Power Dissipation	- Derate Above 25°C		2.38	W/°C
T _J , T _{STG}	Operating and Storage Temper	Operating and Storage Temperature Range			°C
TL	Maximum Lead Temperature fo	r Soldering, 1/8" from Case for 5 S	econds	300	οС

Thermal Characteristics

Symbol	Parameter FCH150N65F_F155			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.42	°C/W	
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max. 40			

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCH150N65F_F155	FCH150N65F	TO-247 G03	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	lest Conditions	Min.	iyp.	Max.	Unit
Off Charac	cteristics					
D\/	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
BV _{DSS} Drain to Source	Dialii to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 10 \text{ mA}, T_J = 150^{\circ}\text{C}$	700	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, Referenced to 25°C	-	0.72	-	V/°C
I	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	10	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 520 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	86	-	μА
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 2.4$ mA	3	-	5	V
R _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$	-	133	150	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 12 A	-	22	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz		2810	3737	pF
C _{oss}	Output Capacitance			91	121	pF
C _{rss}	Reverse Transfer Capacitance			0.77	-	pF
C _{oss}	Output Capacitance	$V_{DS} = 380 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	54	-	pF
Coss eff.	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		361	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 380 V, I _D = 12 A,		72	94	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	15	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	31	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.69	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time	V _{DD} = 380 V, I _D = 12 A,	-	28	66	ns
t _r	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_{g} = 4.7 \Omega$	-	15	40	ns
t _{d(off)}	Turn-Off Delay Time		-	73	156	ns
t _f	Turn-Off Fall Time	(Note 4)	-	6	22	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current			-	24	Α
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	72	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 12 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 12 A,	-	123	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	597	-	nC

Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I_{AS} = 4.7 A, R_{G} = 25 Ω , Starting T_{J} = 25°C.
- 3. I $_{SD} \leq$ 12 A, di/dt \leq 200 A/µs, V $_{DD} \leq$ 380 V, Starting T $_{J}$ = 25°C.
- ${\bf 4.} \ {\bf Essentially \ independent \ of \ operating \ temperature}.$

Typical Performance Characteristics

Figure 1. On-Region Characteristics

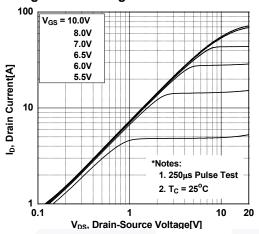


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

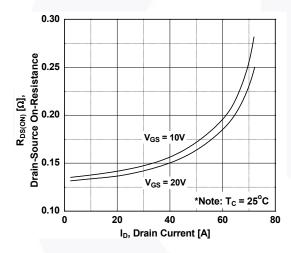


Figure 5. Capacitance Characteristics

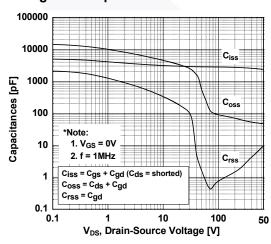


Figure 2. Transfer Characteristics

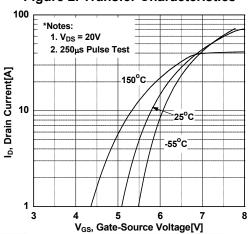


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

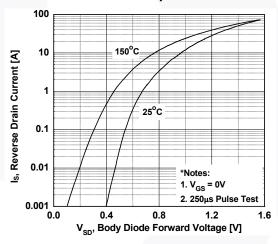
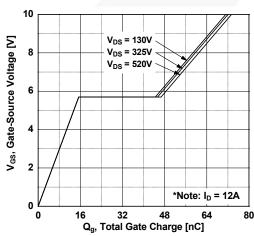


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

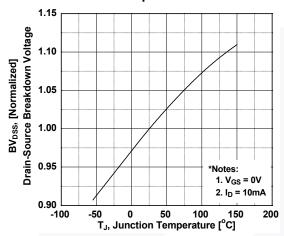


Figure 9. Maximum Safe Operating Area

-100

-50

0

Figure 8. On-Resistance Variation

vs. Temperature

Figure 10. Maximum Drain Current vs. Case Temperature

50

T_J, Junction Temperature [°C]

100

150

200

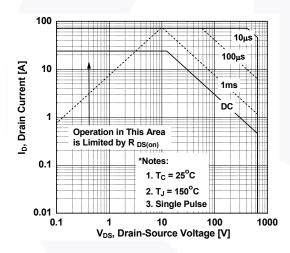
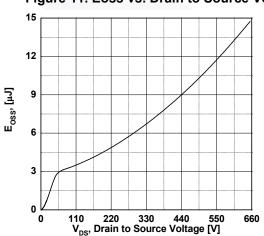
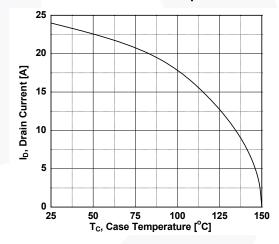


Figure 11. Eoss vs. Drain to Source Voltage



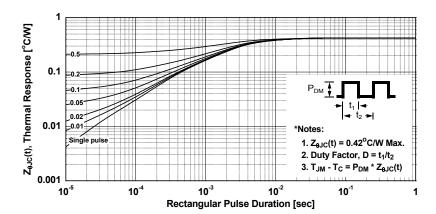


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Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



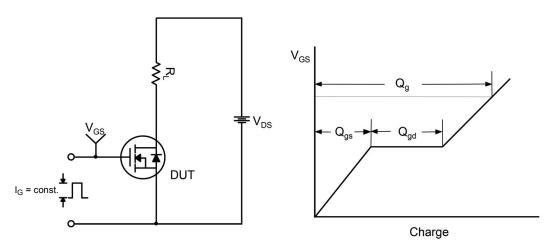


Figure 13. Gate Charge Test Circuit & Waveform

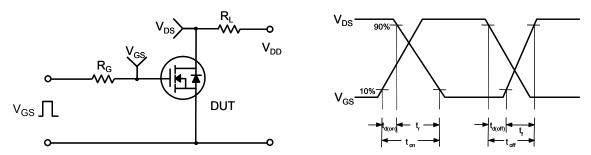


Figure 14. Resistive Switching Test Circuit & Waveforms

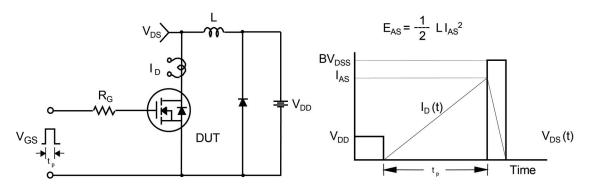
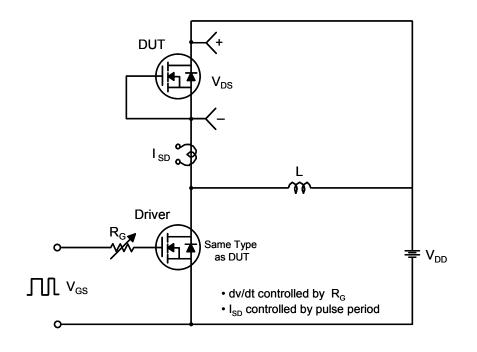


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



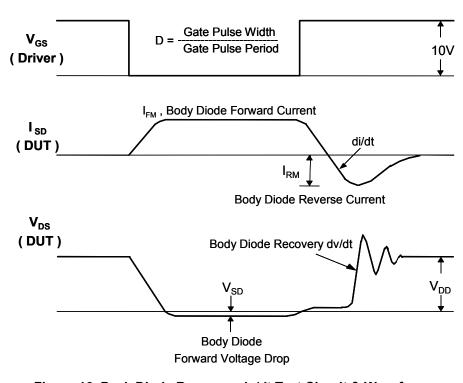
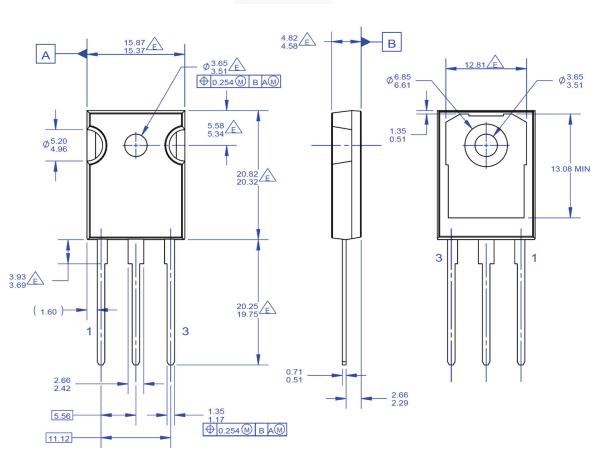


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



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Figure 17. TO-247, Molded, 3-Lead, Jedec AB Long Leads

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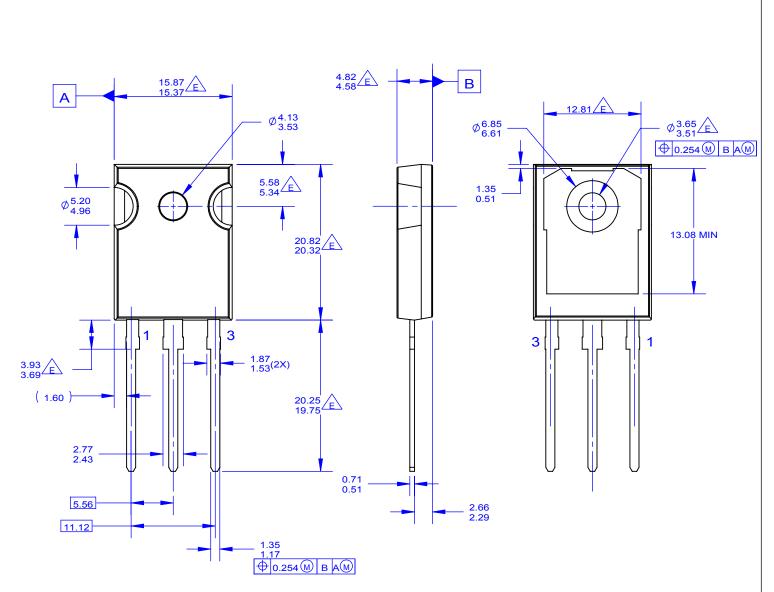
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